## SPS252010C SERIES

### 1. PART NO. EXPRESSION:

 $\frac{SPS}{(a)} \frac{252010C}{(b)} \frac{4R7}{(c)} \frac{YF}{(d)(e)}$ 

(a) Series code

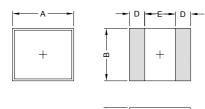
(d) Tolerance code : Y=±30%

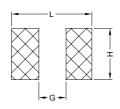
(b) Dimension code

(e) F: RoHS Compliant

(c) Inductance code : 4R7 = 4.70uH

### 2. CONFIGURATION & DIMENSIONS:



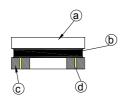


Recommended PCB Pattern

Unit:m/m

А	В	С	D	Е	L	G	Н
2.5 -0.1/+0.3	2.0 -0.05/+0.35	1.02 Max.	0.85 Ref.	0.80 Ref.	2.9 Ref.	0.8 Ref.	2.4 Ref.

### 3. MATERIALS:



(a) Core: Ferrite N4 Core

(b) Coating : Epoxy

(c) Termination : Tin Pb Free(d) Wire : Enameled Copper Wire

### 4. GENERAL SPECIFICATION:

a) ambient temp.: 25°C

b) Isat: Based on inductance change ( $\Delta L/L0$ :  $\leq$  -30%)

c) Irms: Based on temperature rise (ΔT: 40°C)

d) Operating temp. : -40  $^{\circ}$ C to 85  $^{\circ}$ C(for products in unopened tape package, less than 40  $^{\circ}$ C)

Pb RoHS Compliant

NOTE: Specifications subject to change without notice. Please check our website for latest information.



## SPS252010C SERIES

### 5. ELECTRICAL CHARACTERISTICS:

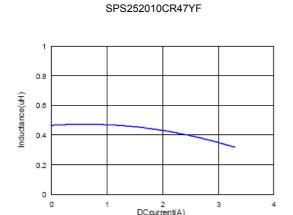
Part No.	Inductance ( uH )	Test Frequency ( Hz )	RDC (Ω)±20%	Isat (A) Typ.	Isat (A) Max.	Irms (A) Typ.	Irms (A) Max.
SPS252010CR47YF	0.47±30%	0.1V/1M	0.030	2.85	2.57	2.80	2.50
SPS252010CR68YF	0.68±30%	0.1V/1M	0.039	2.70	2.45	2.40	2.20
SPS252010C1R0YF	1.0±30%	0.1V/1M	0.055	2.20	1.89	2.20	1.80
SPS252010C1R5YF	1.5±30%	0.1V/1M	0.075	1.90	1.58	1.80	1.50
SPS252010C2R2MF	2.2±20%	0.1V/1M	0.100	1.62	1.39	1.68	1.30
SPS252010C3R3MF	3.3±20%	0.1V/1M	0.145	1.30	1.17	1.34	1.10
SPS252010C4R7MF	4.7±20%	0.1V/1M	0.215	1.20	1.08	1.10	1.00
SPS252010C6R8MF	6.8±20%	0.1V/1M	0.315	0.90	0.77	0.90	0.80
SPS252010C100MF	10±20%	0.1V/1M	0.420	0.73	0.65	0.82	0.65
SPS252010C150MF	15±20%	0.1V/1M	0.600	0.55	0.50	0.55	0.50
SPS252010C220MF	22±20%	0.1V/1M	0.830	0.50	0.40	0.40	0.35

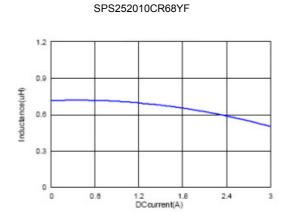


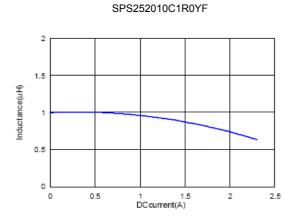
NOTE: Specifications subject to change without notice. Please check our website for latest information.

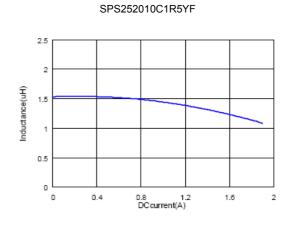
## SPS252010C SERIES

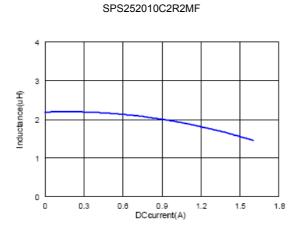
### 6. CHARACTERISTICS CURVES:

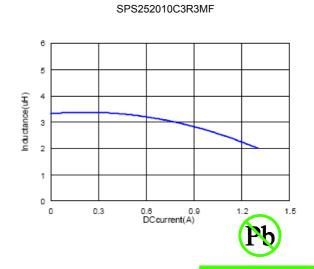












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26.02.2013

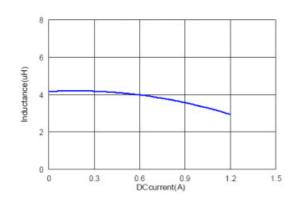
**RoHS Compliant** 



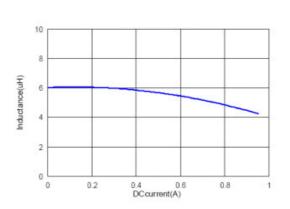
## SPS252010C SERIES

### 6. CHARACTERISTICS CURVES:

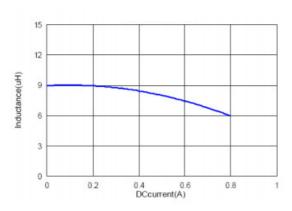




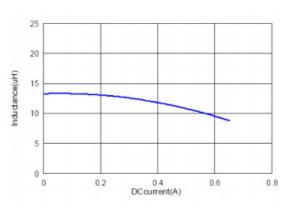
### SPS252010C6R8MF



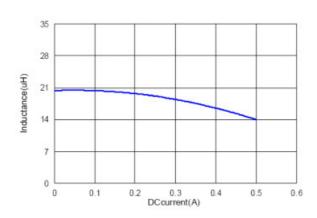
SPS252010C100MF



SPS252010C150MF



### SPS252010C220MF





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## SPS252010C SERIES

### 7. RELIABILITY AND TEST CONDITION

ITEM	PERFORMANCE	TEST CONDITION
Electrical Characteristics	Test	
Inductance L Q	Refer to standard electrical characteristics list	Agilent-4291, Agilent-4287 Agilent-4192, Agilent-4285
SRF	_	Agilent-4291
DC Resistance	_	Agilent-4338
Rated Current	Base on temp. rise & ΔL/L0A□30%.	Saturation DC Current (Isat) will cause L0 to drop approximately $\Delta$ L(%).
Temperature Rise Test	ΔT 40°CMax	Heat Rated Current (Irms) will cause the coil temperature rise approximately $\Delta T(^{\circ}C)$ without core loss. 1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer
Mechanical Performance	Test	
Resistance to Soldering Heat MIL-STD-202 METHOD 210	Inductors shall be no evidence of electrical and and mechanical damage.     Inductance: within ±10% of initial value	Temp.: 260±5°C Time: 10±1.0 Sec
Solderability Test ANSI/J-STD-002	More than 95% of terminal electrode should be covered with solder.	Preheating Dipping Natural cooling  150°C  150°C  After fluxing,component shall be dipped in a melted solder bath at 235±5°C for 4±1seconds.
Reliability Test		
Humidity Test MIL-STD-202 METHOD 103	Visual examination : No mechanical damage     Inductance : within±10% of initial value	Temperature : 40±2°C Humidity : 90-95% Time : 500±8 hrs Measured at room temperature after placing for 2 to 3hrs
Thermal Shock MIL-STD-202 METHOD 107		Conditions for 1 cycle.  Step Temperature (°C) Times (min.)  1 -55±2 30±3 2 Room Temperature Within5 3 85±5 30±3  Total:100 cycles  Measured at room temperature after placing for 2 to 3 hrs



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## SPS252010C SERIES

### 7. RELIABILITY & TEST CONDITION:

ITEM	PERFORMANCE	TEST CONDITION
High Temperature Life Test MIL-STD-202 METHOD 108		Temperature : 85±2°C Duration : 500±8 hrs. Measured at room temperature after placing for 2 to 3 hrs
Low Temperature Storage Test JESD22-A119		Temperature : -40±2°C Duration : 500±8 hrs. Measured at room temperature after placing for 2 to 3 hrs
Humidity Resistance Test MIL-STD-202 METHOD 103		Temperature:40±2°C Humidity:90~ 95% Time:500±8hr. Recovery:2 to 3hrs of recovery under the standard condition after the removal from test chamber.
Random Vibration Test MIL-STD-202 Method 204	Appearance: Cracking, shipping and any other defects harmful to the characteristics should not be allowed.  Impedance: within±30%	Frequency: 10-55-10Hz for 15 min.  Amplitude: 1.52mm  Directions and times:  X, Y, Z directions for 15 min.  This cycle shall be performed 12 times in each of three mutually perpendicular directions (Total 9hours).



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### SPS252010C SERIES

### 8. SOLDERING AND MOUNTING:

### 8-1. Soldering

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

### 8-1.1 Lead Free Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

### 8-1.2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (max)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4-5 secs.

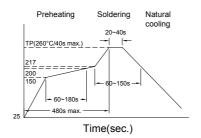


Figure 1. Re-flow Soldering : 3 times max.

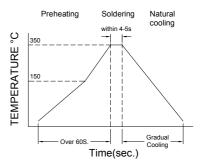


Figure 2. Iron Soldering: 1 times max.



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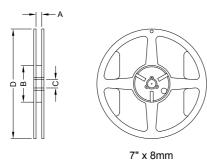


## SPS252010C SERIES

### 9. PACKAGING INFORMATION:

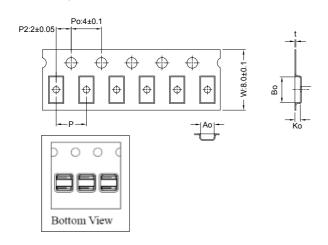
### 9-1. Reel Dimension

## SPS252010C SERIES



Туре	A(mm)	B(mm)	C(mm)	D(mm)
7" x 8mm	8.4±1.0	50 Min.	13±0.8	178±2

### 9-2 Tape Dimension / 8mm



Series	Ao(mm)	Bo(mm)	Ko(mm)	P(mm)	t(mm)
SPS252010	2.45±0.1	3.10±0.1	1.40±0.1	4.2±0.05	0.23±0.05

### 9-3. Packaging Quantity

Size	SPS252010
Chip / Reel	2000

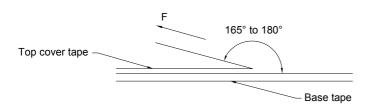


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## SPS252010C SERIES

### 9-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300

### **Application Notice**

### 1. Storage Conditions:

To maintain the solderabililty of terminal electrodes :

- a) Temperature and humidity conditions: Less than 40°C and 60% RH.
- b) Recommended products should be used within 12 months from the time of delivery.
- c) The packaging material should be kept where no chlorine or sulfur exists in the air.

### 2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) The use of tweezers or vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.



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